

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1.     **(Original)** An inverter device, comprising:
  - a plurality of semiconductor chips that are connected in parallel and constitute an arm of an inverter;
  - a first conductor to which a face on one side of said plurality of semiconductor chips is connected;
  - a wide conductor to which a face on the other side of said plurality of semiconductor chips is connected;
  - a second conductor connected to said wide conductor; and
  - a cooler to which said first conductor and second conductor are connected through an insulating resin sheet.
  
2.     **(Original)** An inverter device, comprising:
  - a first semiconductor chip group wherein a plurality of semiconductor chips constituting an upper arm of an inverter are connected in parallel;
  - a first conductor to which faces on one side of said conductor chips of said first semiconductor chip group are connected;
  - a second semiconductor chip group wherein a plurality of semiconductor chips constituting a lower arm of said inverter are connected in parallel;
  - a second conductor to which faces on one side of said semiconductor chips of said second semiconductor chip group are connected;
  - a first wide conductor to which faces on the other side of the semiconductor chips of said first semiconductor chip group are connected;
  - a second wide conductor to which faces on the other side of said semiconductor chips of said second semiconductor chip group are connected;

a third conductor connected with a three-phase output electrode connected to said first wide conductor and arranged between said first conductor and second conductor;

a fourth conductor connected with a negative electrode connected with said second wide conductor and arranged between said first conductor and second conductor; and

a cooler to which said first to fourth conductors are connected through an insulating resin sheet.

3. **(Currently amended)** The inverter device according to claim 1 ~~or~~ 2, further comprising:

a heat buffer plate connected to said wide conductor at a face on the other side of said semiconductor chip.

4. **(Original)** A method of manufacturing an inverter device, comprising:

bonding a plurality of semiconductor chips and a heat buffer plate by a low melting point or high melting point solder;

bonding said heat buffer plate and a conductor by a low melting point or high melting point solder;

fixing said conductor to a cooler; and

fixing said heat buffer plate and a wide conductor.

5. **(Original)** The method of manufacturing an inverter device according to claim 4, further comprising:

dividing said wide conductor into a plurality of chips; and

fixing said conductor and said cooler by application of pressure at locations where a plurality of semiconductor chips are not bonded to said conductor.

6. **(Original)** An electric automobile, comprising:

(1) an inverter device comprising:

a plurality of semiconductor chips that are connected in parallel and constitute an arm of an inverter;

a first conductor to which a face on one side of said plurality of semiconductor chips is connected;

a wide conductor to which a face on the other side of said plurality of semiconductor chips is connected;

a second conductor connected to said wide conductor;

a cooler to which said first conductor and second conductor are connected through an insulating resin sheet; and

(2) an electric motor incorporating said inverter device and that drives a drive wheel by using an AC power from said inverter device.

7. **(Original)** An electric automobile, comprising:

(1) an inverter device comprising:

a plurality of semiconductor chips that are connected in parallel and constitute an arm of an inverter;

a first conductor to which a face on one side of said plurality of semiconductor chips is connected;

a wide conductor to which a face on the other side of said plurality of semiconductor chips is connected;

a second conductor connected to said wide conductor;

a cooler to which said first conductor and second conductor are connected through an insulating resin sheet;

(2) an electric motor incorporating said inverter device and that drives a drive wheel by using an AC power from said inverter device; and

(3) an internal combustion engine that drives said drive wheel and is provided in addition to said electric motor.

8. **(New)** The inverter device according to claim 2, further comprising:

a heat buffer plate connected to said wide conductor at a face on the other side of said semiconductor chip.